Binary Up/Down Counter

The MC14516B synchronous up/down binary counter is constructed with MOS P-channel and N-channel enhancement mode devices in a monolithic structure.

This counter can be preset by applying the desired value, in binary, to the Preset inputs (P0, P1, P2, P3) and then bringing the Preset Enable (PE) high. The direction of counting is controlled by applying a high (for up counting) or a low (for down counting) to the UP/DOWN input. The state of the counter changes on the positive transition of the clock input.

Cascading can be accomplished by connecting the Carry Out to the Carry In of the next stage while clocking each counter in parallel. The outputs (Q0, Q1, Q2, Q3) can be reset to a low state by applying a high to the reset (R) pin.

This CMOS counter finds primary use in up/down and difference counting. Other applications include: (1) Frequency synthesizer applications where low power dissipation and/or high noise immunity is desired, (2) Analog–to–digital and digital–to–analog conversions, and (3) Magnitude and sign generation.

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- · Internally Synchronous for High Speed
- Logic Edge—Clocked Design Count Occurs on Positive Going Edge of Clock
- · Single Pin Reset
- Asynchronous Preset Enable Operation
- Capable of Driving Two Low–Power TTL Loads or One Low–Power Schottky Load Over the Rated Temperature Range

MAXIMUM RATINGS* (Voltages Referenced to VSS)

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage	- 0.5 to + 18.0	V
V _{in} , V _{out}	Input or Output Voltage (DC or Transient)	-0.5 to $V_{DD} + 0.5$	V
I _{in} , I _{out}	Input or Output Current (DC or Transient), per Pin	± 10	mA
PD	Power Dissipation, per Package†	500	mW
T _{stg}	Storage Temperature	- 65 to + 150	°C
TL	Lead Temperature (8–Second Soldering)	260	°C

^{*} Maximum Ratings are those values beyond which damage to the device may occur. †Temperature Derating:

Plastic "P and D/DW" Packages: – 7.0 mW/°C From 65°C To 125°C Ceramic "L" Packages: – 12 mW/°C From 100°C To 125°C

TRUTH TABLE

Carry In	Up/Down	Preset Enable	Reset	Clock	Action
1	Х	0	0	Х	No Count
0	1	0	0		Count Up
0	0	0	0		Count Down
Х	Х	1	0	Х	Preset
Х	Х	Х	1	Х	Reset

X = Don't Care

NOTE: When counting up, the Carry Out signal is normally high and is low only when Q0 through Q3 are high and Carry In is low. When counting down, Carry Out is low only when Q0 through Q3 and Carry In are low.

MC14516B



L SUFFIX CERAMIC CASE 620



P SUFFIX PLASTIC CASE 648

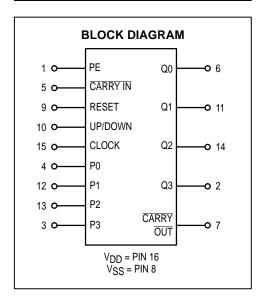


D SUFFIX SOIC CASE 751B

ORDERING INFORMATION

MC14XXXBCP Plastic
MC14XXXBCL Ceramic
MC14XXXBD SOIC

 $T_A = -55^\circ$ to 125°C for all packages.



This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either VSS or VDD). Unused outputs must be left open.



ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

			V _{DD}	- 5	5°C		25°C		125	5°C	
Characteristic		Symbol	Vdc	Min	Max	Min	Тур#	Max	Min	Max	Unit
Output Voltage V _{in} = V _{DD} or 0	"0" Level	VOL	5.0 10 15	_ _ _	0.05 0.05 0.05	_ _ _	0 0 0	0.05 0.05 0.05	_ _ _	0.05 0.05 0.05	Vdc
V _{in} = 0 or V _{DD}	"1" Level	VOH	5.0 10 15	4.95 9.95 14.95	_ _ _	4.95 9.95 14.95	5.0 10 15	_ _ _	4.95 9.95 14.95	_ _ _	Vdc
Input Voltage (V _O = 4.5 or 0.5 Vdc) (V _O = 9.0 or 1.0 Vdc) (V _O = 13.5 or 1.5 Vdc)	"0" Level	V _I L	5.0 10 15	_ _ _	1.5 3.0 4.0		2.25 4.50 6.75	1.5 3.0 4.0	_ _ _	1.5 3.0 4.0	Vdc
$(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	"1" Level	VIH	5.0 10 15	3.5 7.0 11	_ _ _	3.5 7.0 11	2.75 5.50 8.25	_ _ _	3.5 7.0 11	=	Vdc
Output Drive Current (V _{OH} = 2.5 Vdc) (V _{OH} = 4.6 Vdc) (V _{OH} = 9.5 Vdc) (V _{OH} = 13.5 Vdc)	Source	ІОН	5.0 5.0 10 15	- 3.0 - 0.64 - 1.6 - 4.2	_ _ _ _	- 2.4 - 0.51 - 1.3 - 3.4	- 4.2 - 0.88 - 2.25 - 8.8		- 1.7 - 0.36 - 0.9 - 2.4	_ _ _ _	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	Sink	lOL	5.0 10 15	0.64 1.6 4.2	_ _ _	0.51 1.3 3.4	0.88 2.25 8.8	_ _ _	0.36 0.9 2.4	_ _ _	mAdc
Input Current		l _{in}	15	_	± 0.1	_	±0.00001	± 0.1	_	± 1.0	μAdc
Input Capacitance (V _{in} = 0)		C _{in}	_	_	_	_	5.0	7.5	_	_	pF
Quiescent Current (Per Package)		IDD	5.0 10 15	_ _ _	5.0 10 20		0.005 0.010 0.015	5.0 10 20	_ _ _	150 300 600	μAdc
Total Supply Current**† (Dynamic plus Quiesce Per Package) (C _L = 50 pF on all outp buffers switching)		lΤ	5.0 10 15			$I_{T} = (1$.58 μΑ/kHz) † .20 μΑ/kHz) † .70 μΑ/kHz) †	f + I _{DD}			μAdc

[#]Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

where: I_T is in μ A (per package), C_L in pF, V = (V_{DD} – V_{SS}) in volts, f in kHz is input frequency, and k = 0.001.

PIN ASSIGNMENT 16 V_{DD} Q3 🛮 2 15 C 14 🛮 Q2 P3 🛚 3 P0 🛮 4 13 P2 CARRY IN [5 12 P1 11 🛮 Q1 Q0 [6 CARRY OUT [7 10 U/D V_{SS} [] 8 9] R

^{**} The formulas given are for the typical characteristics only at 25 $^{\circ}\text{C}.$

[†]To calculate total supply current at loads other than 50 pF:

			All Types			_
Characteristic	Symbol	V _{DD}	Min	Тур#	Max	Unit
Output Rise and Fall Time t_{TLH} , t_{THL} = (1.5 ns/pF) C_L + 25 ns t_{TLH} , t_{THL} = (0.75 ns/pF) C_L + 12.5 ns t_{TLH} , t_{THL} = (0.55 ns/pF) C_L + 9.5 ns	tTLH, tTHL	5.0 10 15	_ _ _	100 50 40	200 100 80	ns
Propagation Delay Time Clock to Q tpLH, tpHL = (1.7 ns/pF) C _L + 230 ns tpLH, tpHL = (0.66 ns/pF) C _L + 97 ns tpLH, tpHL = (0.5 ns/pF) C _L + 75 ns	^t PLH, ^t PHL	5.0 10 15	_ _ _	315 130 100	630 260 200	ns
Clock to $\overline{\text{Carry Out}}$ tp_{LH} , tp_{HL} = (1.7 ns/pF) C_{L} + 230 ns tp_{LH} , tp_{HL} = (0.66 ns/pF) C_{L} + 97 ns tp_{LH} , tp_{HL} = (0.5 ns/pF) C_{L} + 75 ns	^t PLH, ^t PHL	5.0 10 15	_ _ _	315 130 100	630 260 200	ns
Carry In to Carry Out tp_{LH} , $tp_{HL} = (1.7 \text{ ns/pF}) C_L + 230 \text{ ns}$ tp_{LH} , $tp_{HL} = (0.66 \text{ ns/pF}) C_L + 97 \text{ ns}$ tp_{LH} , $tp_{HL} = (0.5 \text{ ns/pF}) C_L + 75 \text{ ns}$	^t PLH, ^t PHL	5.0 10 15	_ _ _	180 80 60	360 160 120	ns
Preset or Reset to Q tpLH, tpHL = (1.7 ns/pF) CL + 230 ns tpLH, tpHL = (0.66 ns/pF) CL + 97 ns tpLH, tpHL = (0.5 ns/pF) CL + 75 ns	^t PLH [,] ^t PHL	5.0 10 15	_ _ _	315 130 100	630 360 200	ns
Preset or Reset to \overline{C} arry \overline{O} ut tpLH, tpHL = (1.7 ns/pF) CL + 465 ns tpLH, tpHL = (0.66 ns/pF) CL + 192 ns tpLH, tpHL = (0.5 ns/pF) CL + 125 ns	^t PLH [,] ^t PHL	5.0 10 15	_ _ _	550 225 150	1100 450 300	ns
Reset Pulse Width	t _W	5.0 10 15	380 200 160	190 100 80	_ _ _	ns
Clock Pulse Width	tWH	5.0 10 15	350 170 140	200 100 75		ns
Clock Pulse Frequency	f _C l	5.0 10 15	_ _ _	3.0 6.0 8.0	1.5 3.0 4.0	MHz
Preset or Reset Removal Time The Preset or Reset signal must be low prior to a positive–going transition of the clock.	^t rem	5.0 10 15	650 230 180	325 115 90	_ _	ns
Clock Rise and Fall Time	tTLH, tTHL	5.0 10 15	_ _ _	_ _ _	15 5 4	μѕ
Setup Time Carry In to Clock	^t su	5.0 10 15	260 120 100	130 60 50	_ _ _	ns
Hold Time Clock to Carry In	^t h	5.0 10 15	0 20 20	- 60 - 20 0		ns
Setup Time Up/Down to Clock	^t su	5.0 10 15	500 200 150	250 100 75	=	ns
Hold Time Clock to Up/Down	th	5.0 10 15	- 70 - 10 0	- 160 - 60 - 40	_ _ _	ns
Setup Time Pn to PE	t _{su}	5.0 10 15	- 40 - 30 - 25	- 120 - 70 - 50	_ _ _	ns
Hold Time PE to Pn	t _h	5.0 10 15	480 420 420	240 210 210	_ _ _	ns
Preset Enable Pulse Width	^t WH	5.0 10 15	200 100 80	100 50 40		ns

^{*} The formulas given are for the typical characteristics only at 25°C.

#Data labelled "Typ" is not to be used for design purposes but is intended as an Indication of the IC's potential performance.

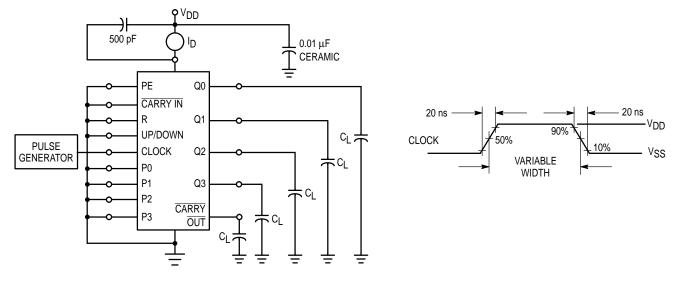
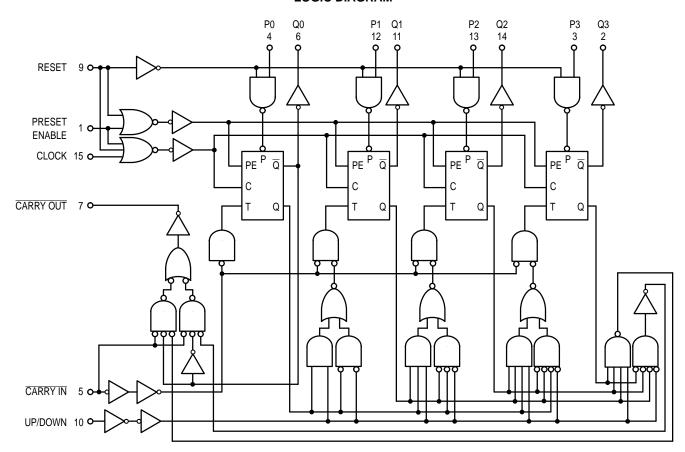
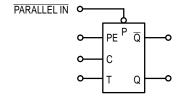


Figure 1. Power Dissipation Test Circuit and Waveform

LOGIC DIAGRAM



TOGGLE FLIP-FLOP



FLIP-FLOP FUNCTIONAL TRUTH TABLE

Preset Enable	Clock	Т	Q _{n+1}
1	Х	Х	Parallel In
0		0	Q _n
0		1	\overline{Q}_n
0	~	Х	Qn

X = Don't Care

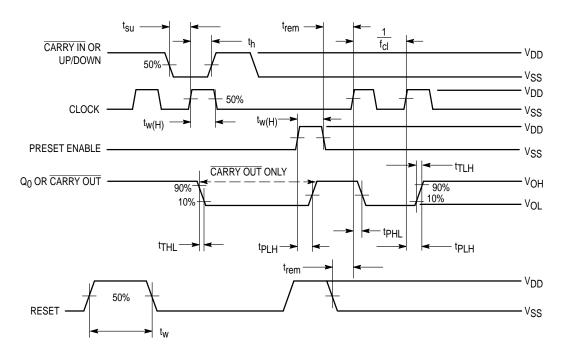


Figure 2. Switching Time Waveforms

PIN DESCRIPTIONS

INPUTS

P0, P1, P2, P3, Preset Inputs (Pins 4, 12, 13, 3) — Data on these inputs is loaded into the counter when PE is taken high.

Carry In, (Pin 5) — This active—low input is used when Cascading stages. Carry In is usually connected to Carry Out of the previous stage. While high, Clock is inhibited.

Clock, (Pin 15) — Binary data is incremented or decremented, depending on the direction of count, on the positive transition of this input.

OUTPUTS

Q0, Q1, Q2, Q3, Binary outputs (Pins 6, 11, 14, 2) — Binary data is present on these outputs with Q0 corresponding to the least significant bit.

Carry Out, (Pin 7) — Used when cascading stages, Carry Out is usually connected to Carry In of the next stage. This

synchronous output is active low and may also be used to indicate terminal count.

CONTROLS

PE, **Preset Enable**, **(Pin 1)** — Asynchronously loads data on the Preset Inputs. This pin is active high and inhibits the clock when high.

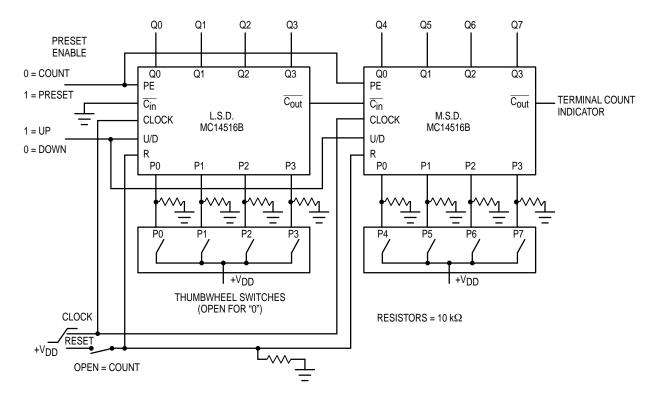
R, Reset, (Pin 9) — Asynchronously resets the Q outputs to a low state. This pin is active high and inhibits the clock when high.

Up/Down, (Pin 10) — Controls the direction of count, high for up count, low for down count.

SUPPLY PINS

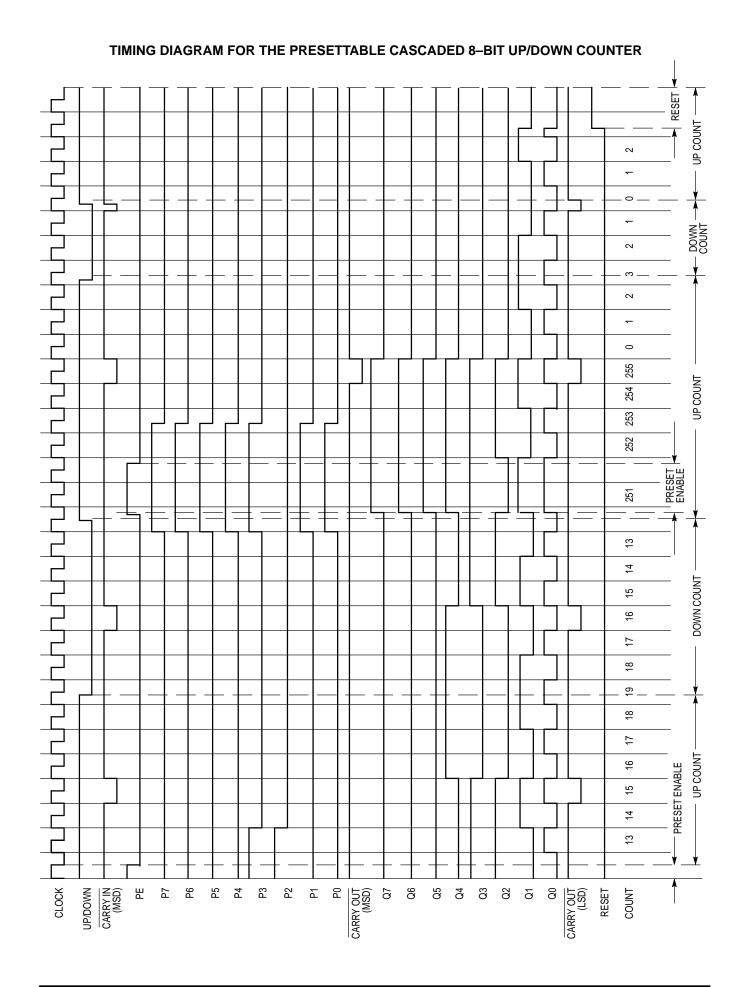
 $\ensuremath{\text{VSS}},$ Negative Supply Voltage, (Pin 8) — This pin is usually connected to ground.

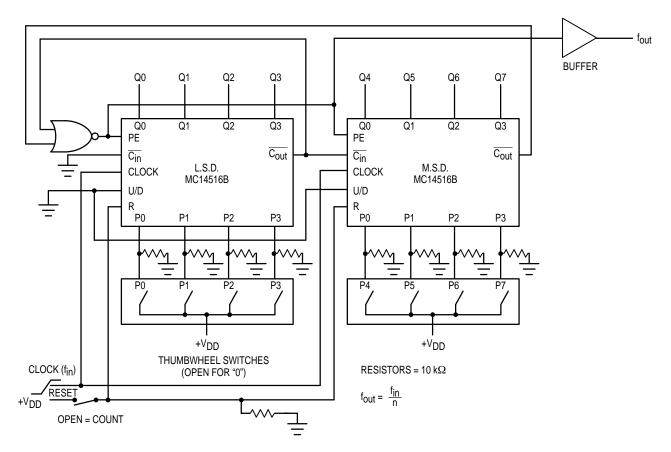
VDD, Positive Supply Voltage, (Pin 16) — This pin is connected to a positive supply voltage ranging from 3.0 volts to 18.0 volts.



NOTE: The Least Significant Digit (L.S.D.) counts from a preset value once Preset Enable (PE) goes low. The Most Significant Digit (M.S.D.) is disabled while $\overline{C_{in}}$ is high. When the count of the L.S.D. reaches 0 (count down mode) or reaches 15 (count up mode), $\overline{C_{out}}$ goes low for one complete clock cycle, thus allowing the next counter to decrement/increment one count. (See Timing Diagram) The L.S.D. now counts through another cycle (15 clock pulses) and the above cycle is repeated.

Figure 3. Presettable Cascaded 8-Bit Up/Down Counter



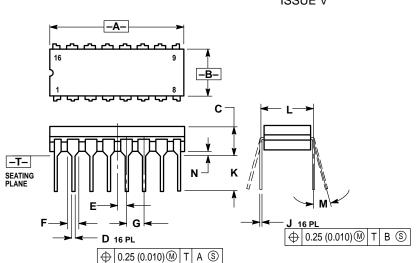


NOTE: The programmable frequency divider can be set by applying the desired divide ratio, in binary, to the preset inputs. For example, the maximum divide ratio of 255 may be obtained by applying a 1111 1111 to the preset inputs P0 to P7. For this divide operation, both counters should be configured in the count down mode. The divide ratio of zero is an undefined state and should be avoided.

Figure 4. Programmable Cascaded Frequency Divider

OUTLINE DIMENSIONS

L SUFFIX CERAMIC DIP PACKAGE CASE 620-10 ISSUE V



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

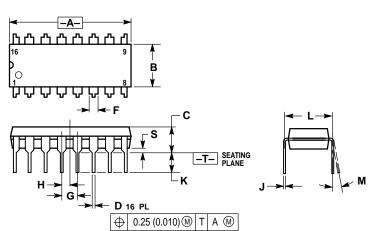
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.

 4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC RODY.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.750	0.785	19.05	19.93
В	0.240	0.295	6.10	7.49
C		0.200		5.08
D	0.015	0.020	0.39	0.50
Е	0.050	BSC	1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100	BSC	2.54 BSC	
Н	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300	0.300 BSC		BSC
М	0°	15°	0 °	15°
N	0.020	0.040	0.51	1.01

P SUFFIX

PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

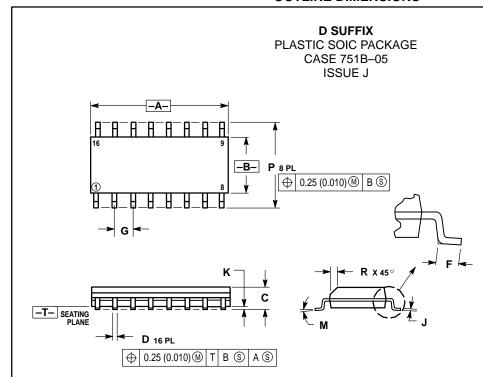
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10°	0°	10 °	
S	0.020	0.040	0.51	1.01	

OUTLINE DIMENSIONS



- DIMENSIONING AND TOLERANCING PER ANSI
- CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.

 MAXIMUM MOLD PROTRUSION 0.15 (0.006)
- PER SIDE.
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	METERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
Р	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

Motorola reserves the right to make changes without further notice to any products herein. Motorola makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Motorola assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters which may be provided in Motorola data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Motorola does not convey any license under its patent rights nor the rights of others. Motorola products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Motorola product could create a situation where personal injury or death may occur. Should Buyer purchase or use Motorola products for any such unintended or unauthorized application, Buyer shall indemnify and hold Motorola and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Motorola was negligent regarding the design or manufacture of the part. Motorola and Marare registered trademarks of Motorola, Inc. Motorola, Inc. is an Equal Opportunity/Affirmative Action Employer.

USA/EUROPE/Locations Not Listed: Motorola Literature Distribution; P.O. Box 20912: Phoenix. Arizona 85036. 1-800-441-2447 or 602-303-5454

MFAX: RMFAX0@email.sps.mot.com - TOUCHTONE 602-244-6609 INTERNET: http://Design-NET.com

JAPAN: Nippon Motorola Ltd.; Tatsumi-SPD-JLDC, 6F Seibu-Butsuryu-Center, 3-14-2 Tatsumi Koto-Ku, Tokyo 135, Japan. 03-81-3521-8315

ASIA/PACIFIC: Motorola Semiconductors H.K. Ltd.; 8B Tai Ping Industrial Park, 51 Ting Kok Road, Tai Po, N.T., Hong Kong. 852-26629298



